INTEGRATED CIRCUITS



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TDA1581T

FEATURES

- Selective subcarrier amplifier (57 kHz) with gain control
- Transmitter identification signal (SK) decoder
- Area identification signal (BK) and announcement identification signal (DK) active filtering
- BK and DK decoders (Schmitt trigger with switched hysteresis)
- BK and DK switch-on/switch-off delay circuits
- SK and BK control outputs.

QUICK REFERENCE DATA

GENERAL DESCRIPTION

The TDA1581T decoder is for radio transmissions having 57 kHz amplitude-modulated subcarriers as used in the german 'Verkehrs Warnfunk' (VWF) traffic warning system.

Measured in Fig.3 at V_{iSK} = 8 mV; f = 57 kHz amplitude modulated with f_m = 34.95 Hz and m = 60% for 'BK-traffic area C' signal; or with f_m = 125 Hz and m = 30% for DK signal

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _P	supply voltage range		7.5	8.5	10	V
I _P	supply current		-	6	-	mA
V _{iSK}	nominal input voltage	f = 57 kHz	-	8	-	mV
Zi	input impedance	f ≤ 57 kHz	100	-	-	kΩ
V _{iSK}	control level	–3 dB	-	2.4	-	mV
V _{i(p-p)}	input voltage peak-to-peak value		2	-	-	V
m _{BKon}	SK switch-on threshold level		-	42	-	%
Δm_{BK}	SK switch hysteresis		-	3.5	-	dB
t _{dSKon}	SK switch-on delay		-	150	-	ms
t _{dSKoff}	SK switch-off delay		-	750	-	ms
m _{DKon}	DK switch-on threshold level		-	13	-	%
Δm _{DK}	DK switch hysteresis		-	3.6	-	dB
t _{dDKon}	DK switch-on delay		-	750	-	ms
t _{dDKoff}	DK switch-off delay		-	750	-	ms
T _{amb}	operating ambient temperature range		-30	_	+80	°C

ORDERING INFORMATION

EXTENDED		PACKAGE		
TYPE NUMBER	PINS	PIN POSITION	MATERIAL	CODE
TDA1581T	20	SO	plastic	SOT163A ⁽¹⁾

Note

1. SOT163-1; 1996 August 28.

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PINNING

SYMBOL	PIN	DESCRIPTION
n.c.	1	not connected
DK _{out}	2	DK output current
SK _{out}	3	SK output current
τ _{BK}	4	time delay BK
V _{5BK}	5	filter output BK
V _{6BK}	6	filter input BK
VP	7	supply voltage
V _P / 2	8	half supply voltage
V _{9SK}	9	SK detector output
n.c.	10	not connected
n.c.	11	not connected
V _{12SK}	12	57 kHz band pass filter
V _{AGC}	13	AGC
I ₁₄	14	prestage biasing current
V _{MPX}	15	MPX input
V _{16DK}	16	filter input DK
V _{17DK}	17	filter output DK
τ _{DK}	18	time delay DK
I ₁₉	19	reference current for BK, DK detector
GND	20	ground



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LIMITING VALUES

In accordance with the Absolute Maximum System (IEC134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{P} = V_{7-20}$	supply voltage	pin 7	-	-	15	V
V _{2; 3-20}	switch output voltage	pins 2 or 3	-0.5	-	15	V
I _{2; 3}	switch output current	pins 2 or 3	-10	-	5	mA
V ₁₅₋₂₀	signal input voltage	pin 15	-0.5	-	V _P	V
I ₁₅	signal input current	pin 15	-	-	-10	mA
P _{tot}	total power dissipation		-	-	800	mW
T _{stg}	storage temperature range		-55	-	+150	°C
T _{amb}	operating ambient temperature range		-30	-	+80	°C

CHARACTERISTICS

 V_p = 8.5 V; T_{amb} = +25 °C; measured at nominal input signal: V_{iSK} = 8 mV, f = 57 kHz amplitude modulated with f_m = 34.95 Hz and m = 60% for 'BK-traffic area C' signal; or with f_m = 125 Hz and m = 30% for DK signal.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
VP	supply voltage	pin 7	7.5	-	10	V
I _P	supply current	pin 7	-	6	15	mA
SK amplifier/de	ecoder					
Zi	input impedance	f ≤ 57 kHz	60	-	-	kΩ
V _{i(p-p)}	input voltage (peak-to-peak value)		2	-	-	V
V _{iSK}	input voltage at start of gain control	$V_{o9BK} = -3 \text{ dB}$	-	2.4 ⁽¹⁾	-	mV
G _{v9-15}	voltage gain	V _{9BK} / V _{15SK}	_	44(1)	-	dB
ΔG_{v9-15}	gain spread		-	-	±2	dB
ΔG_v	gain control range		40	-	-	dB
V _{o9BK}	controlled output voltage		_	440	_	mV
V _{o9DK}			-	220	_	mV
BK circuit						
V _{o5BKon}	switch-on threshold level	pin 3 high-Z	600	670	750	mV
V _{o5BKon} V _{o5BKoff}	switch hysteresis		3	3.5	4	dB
V _{4-20off}	BK switch threshold level for BK-off (SK-off) (typ. value = $0.21V_{8-20}$)	pin 3 conducting	0.8	0.88	0.97	V
	SK output (pin 3)					
l ₃	permitted load current		_	-	0.5	mA
V _{3-20sat}	saturation voltage	I ₃ = 1.5 mA	-	-	0.35	V
V ₃₋₂₀	rejection voltage	I ₃ < 5 μA	18	_	-	V

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
DK circuit	1			-	-	
V _{17DKon}	switch-on threshold level	pin 2 high-Z	600	670	750	mV
V _{17DKon} V _{17DKoff}	switch hysteresis		3.1	3.6	4.1	dB
V _{18-20off}	DK switch threshold level for DK-off (Schmitt trigger output) (typ. value = $1 \times V_{BE}$)	pin 2 conducting	_	0.6	-	V
	DK output (pin 2)					
l ₂	permitted load current		-	-	0.5	mA
V _{2-20sat}	saturation voltage	l ₂ = 1.5 mA	-	-	0.35	V
V ₂₋₂₀	rejection voltage	I ₂ < 5 μA	18	-	_	V
BK and DK filt	er amplifiers					
Go	open loop gain	f = 100 Hz	84	-	-	dB
Gi	current gain		120	_	_	dB
li	input bias current		-	-	±50	nA
V ₀₅₋₈	output offset voltage	$R_{5-6} = R_{16-17} = 680 \text{ k}\Omega$	-	_	±50	mV
V ₁₇₋₈						
lo	available output current		±1	-	_	mA
R _o	output resistance		-	2	3.5	kΩ
CL	permitted load capacitance		-	-	50	pF
Internal refere	nce voltage					•
V ₈₋₂₀	output voltage (typ. value = 0.5V _P)		4.0	4.25	4.5	V
R ₈	internal resistance of voltage source		_	-	5	Ω
I ₈₋₂₀	available output current		-2	-	_	mA
I ₂₀₋₈			0.6	-	_	mA
I _{8sc}	output short-circuit current (typ. value = $V_P / 1 k\Omega$)		-	-8	-	mA
Reference cur	rent source					
V ₁₉₋₂₀	reference voltage (typ. value = V ₈₋₂₀ – V _{BE})		-	3.6	-	V
R _{i19}	internal biasing resistor		-	5	_	kΩ
R ₁₉₋₂₀	permitted range of external reference resistor		180	-	270	kΩ

Note

1. selectable by R_{14-8} or Z_{12-8} .

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APPLICATION INFORMATION (see Fig.3)

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{iSKon}	SK switch-on threshold level	m _{BK} = 60 %	-	1.8	-	mV
m _{BKon}	SK switch-on threshold level	V _{iSK} = 8 mV	-	32	-	%
m _{BKon} m _{BKoff}	SK switch hysteresis		3.0	3.5	4.0	dB
t _{dSKon}	SK switch-on delay	note 1	_	95	200	ms
t _{dSKoff}	SK switch-off delay	note 2	380	500	700	ms
V _{iDKon}	DK switch-on threshold level	m _{DK} = 30 %	-	1.5	-	mV
m _{DKon}	DK switch-on threshold level	V _{iDK} = 8 mV	_	13	-	%
m _{DKon} m _{DKoff}	DK switch hysteresis		3.1	3.6	4.1	dB
t _{dDKon}	DK switch-on delay	note 1	-	750	1000	ms
t _{dDKoff}	DK switch-off delay	note 2	600	750	1000	ms

Notes to the application information

- 1. Sequence for measuring switch-on delay times (t_{don})
 - a) Nominal BK or DK input signal at pin 15: V_{i(p-p)}= 8 mV; f = 57 kHz; modulation-on.
 - b) Pin 4 of the BK detector (pin 18 of the DK detector) is switched to ground to cause a low signal at the SK output at pin 3 (DK output at pin 2).
 - c) t_{don} commences when the ground connection is removed from pin 4 (pin 18) as the positive-going V_{oBK} signal at pin 5 (V_{oDK} signal at pin 17) crosses zero.

 t_{don} ends when the positive-going edge of the SK output arrives at pin 15 (DK at pin 2).

- 2. Sequence for measuring switch-off delay times (t_{doff})
 - a) Nominal operating conditions as in note 1.
 - b) t_{doff} commences when the input is switched off as the negative-going V_{oBK} signal at pin 5 (V_{oDK} signal at pin 17) crosses zero.

 t_{doff} ends when the negative-going edge of the SK output arrives at pin 3 (DK at pin 2).



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FILTER INFORMATION

Gain

Amplifier conditions: G_o >> G_v and G_o >> 2 \times Q^2

$$G_v = -\frac{\frac{p}{R1 \times C1}}{p^2 + p \times \frac{C1 + C2}{R3 \times C1 \times C2} + \frac{R1 + R2}{R1 \times R2 \times R3 \times C1 \times C2}} \ , \text{ in which} p = j\omega \text{ and } G_v = \frac{V_o}{V_i}$$



	GENERAL EQUATION	C1 = C2 = C	C1 = C2 = C
			R2 << R1
resonance frequency	1	1	11
ω _r =	$\sqrt{\frac{R1 \times R2}{R1 + R2} \times R3 \times C1 \times C2}$	$\frac{1}{C_{\sqrt{\frac{R1 \times R2}{R1 + R2} \times R3}}}$	$C\sqrt{R2 \times R3}$
gain at $\omega = \omega_r$	$\frac{C2}{C1+C2} \times \frac{R3}{R1}$	$\frac{1}{2} \times \frac{R3}{R1}$	$\frac{1}{2} \times \frac{R3}{R1}$
-G _{vr} =	C1 + C2 ^ R1	2^R1	2^R1
quality	$\sqrt{C1 \times C2}$ $\sqrt{R3(R1 + R2)}$	$1 \ \overline{R3(R1+R2)}$	$\frac{1}{2} \times \frac{R3}{R2}$
Q =	$\sqrt{\frac{C1 \times C2}{C1 + C2}} \times \sqrt{\frac{R3(R1 + R2)}{R1 \times R2}}$	$\overline{2}\sqrt{R1 \times R2}$	2 ^ R2

Recommended components

C1, C2	metallized polycarbonate film (MKC) capacitors; $\pm 5\%$
and	
R1, R2, R3	metal film (MR) resistors; ±2%
or	
C1, C2	metallized polyester film (MKT) capacitors; $\pm 5\%$
and	
R1, R2, R3	carbon film (CR) resistors; ±2%

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PACKAGE OUTLINE

SO20: plastic small outline package; 20 leads; body width 7.5 mm



SOT163-1

075E04

MS-013AC

97-05-22

SOT163-1

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Reflow soldering

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

Wave soldering

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured. Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Repairing soldered joints

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
more of the limiting values of the device at these or at	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or may cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification limiting values for extended periods may affect device reliability.
Application information	

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

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